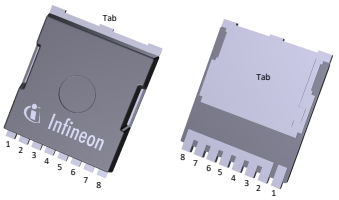
MOSFET

TOLL

StrongIRFET™ 2 Power-Transistor, 100 V



Features

- Optimized for a wide range of applications
- N-Channel, normal level
- 100% avalanche tested
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product validation

Qualified for applications according to the test conditions in the relevant tests of JEDEC JESD22 and J-STD-020.

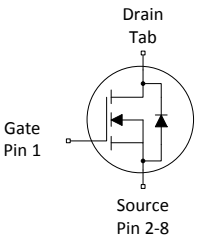


Table 1 Key performance parameters

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(on),max}$	1.75	mΩ
I_D	294	A
Q_{oss}	166	nC
Q_G	130	nC

Hal Pb RoHS

Part number	Package	Marking	Related links
IPT017N10NF2S	PG-HSOF-8	017N10NS	-

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1 Maximum ratings

at T_A=25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Continuous drain current [1]	I_D	-	-	294	A	V_{GS}=10 V, T_C=25 °C
				208		V_{GS}=10 V, T_C=100 °C
				183		V_{GS}=6 V, T_C=100 °C
				33		V_{GS}=10V, T_A=25°C, R_{thJA}=40°C/W [2]
Pulsed drain current [3]	$I_{D,pulse}$	-	-	1176	A	T_A=25 °C
Avalanche energy, single pulse [4]	E_{AS}	-	-	225	mJ	I_D=130 A, R_{GS}=25 Ω
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	300	W	T_C=25 °C
				3.8		T_A=25 °C, R_{thJA}=40 °C/W [2]
Operating and storage temperature	T_j, T_{stg}	-55	-	175	°C	-

[1] Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

[3] See Diagram 3 for more detailed information

[4] See Diagram 13 for more detailed information

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.5	°C/W	-
Thermal resistance, junction - ambient, 6 cm^2 cooling area [5]	R_{thJA}			40		
Thermal resistance, junction - ambient, minimal footprint	R_{thJA}			62		

[5] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

3 Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	V_{GS}=0 V, I_D=1 mA
Gate threshold voltage	$V_{GS(th)}$	2.2	3.0	3.8	V	V_{DS}=V_{GS}, I_D=216 µA
Zero gate voltage drain current	I_{DSS}	-	0.1	1	µA	V_{DS}=100 V, V_{GS}=0 V, T_j=25 °C
			10	100		V_{DS}=100 V, V_{GS}=0 V, T_j=125 °C
Gate-source leakage current	I_{GSS}	-	10	100	nA	V_{GS}=20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	-	1.6	1.75	mΩ	V_{GS}=10 V, I_D=150 A
			1.9	2.2		V_{GS}=6 V, I_D=75 A
Gate resistance	R_G	-	1.3	-	Ω	-
Transconductance [6)]	g_{fs}	125	-	-	S	$\|V_{DS}\|\geq 2\|I_D\|R_{DS(on)max}$, I_D=100 A

6) Defined by design. Not subject to production test.

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	9300	-	pF	V_{GS}=0 V, V_{DS}=50 V, f=1 MHz
Output capacitance	C_{oss}		1400			
Reverse transfer capacitance	C_{rss}		62			
Turn-on delay time	$t_{d(on)}$	-	19	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=100 A, $R_{G,ext}$=1.6 Ω
Rise time	t_r		27			
Turn-off delay time	$t_{d(off)}$		50			
Fall time	t_f		21			

Table 6 Gate charge characteristics [7)]

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	42	-	nC	V_{DD}=50 V, I_D=100 A, V_{GS}=0 to 10 V
Gate charge at threshold	$Q_{g(th)}$		28	-	nC	
Gate to drain charge	Q_{gd}		27	-	nC	
Switching charge	Q_{sw}		41	-	nC	
Gate charge total [8)]	Q_g		130	195	nC	
Gate plateau voltage	$V_{plateau}$		4.5	-	V	
Output charge	Q_{oss}	-	166	-	nC	V_{DS}=50 V, V_{GS}=0 V

7) See "Gate charge waveforms" for parameter definition

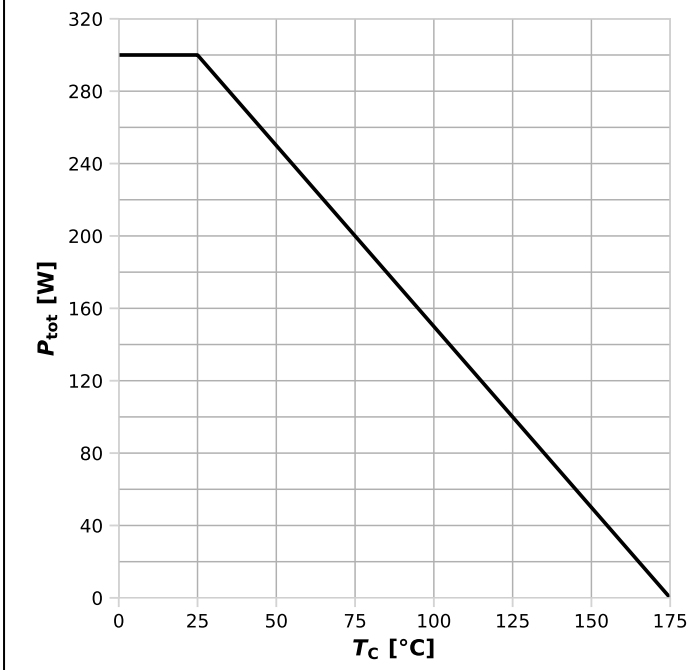
8) Defined by design. Not subject to production test.

Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	214	A	T_C=25 °C
Diode pulse current	$I_{S,pulse}$			1176		
Diode forward voltage	V_{SD}	-	0.85	1.2	V	V_{GS}=0 V, I_F=100 A, T_j=25 °C
Reverse recovery time	t_{rr}	-	47	-	ns	V_R=50 V, I_F=100 A, di_F/dt=500 A/µs
Reverse recovery charge	Q_{rr}		388		nC	

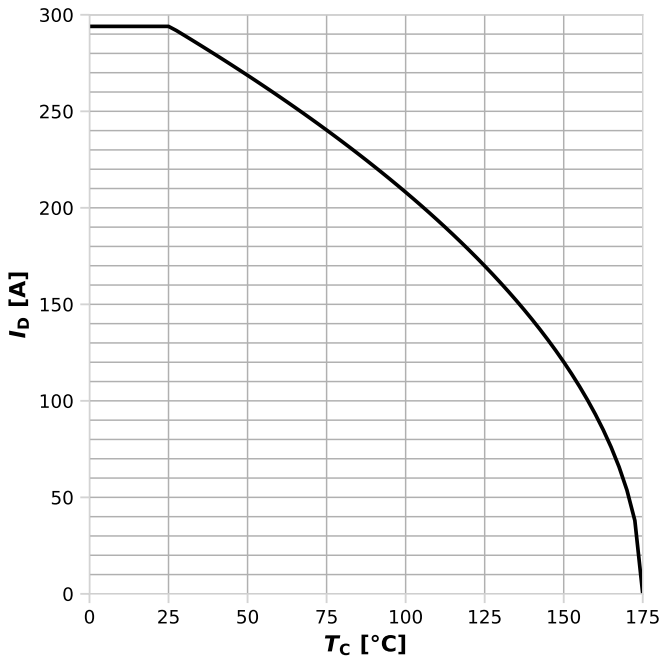
4 Electrical characteristics diagrams

Diagram 1: Power dissipation



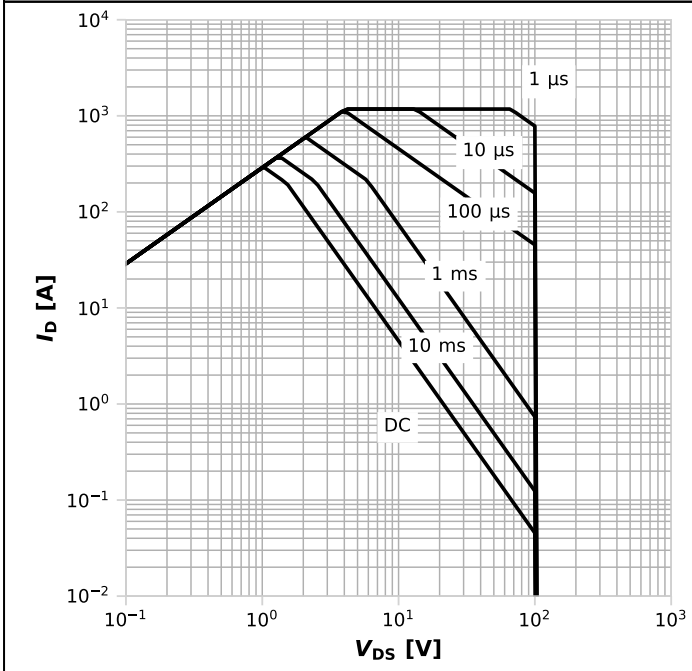
P_{tot}=f(T_C)

Diagram 2: Drain current



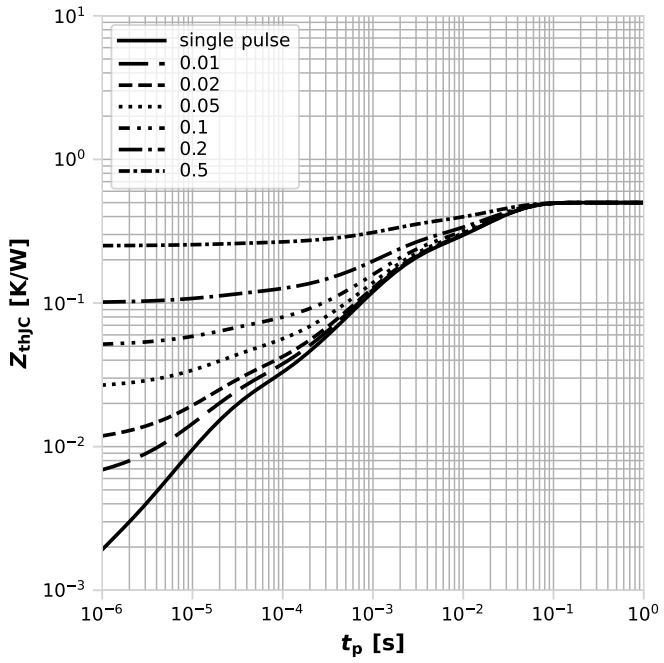
I_D=f(T_C); V_{GS}≥10 V

Diagram 3: Safe operating area



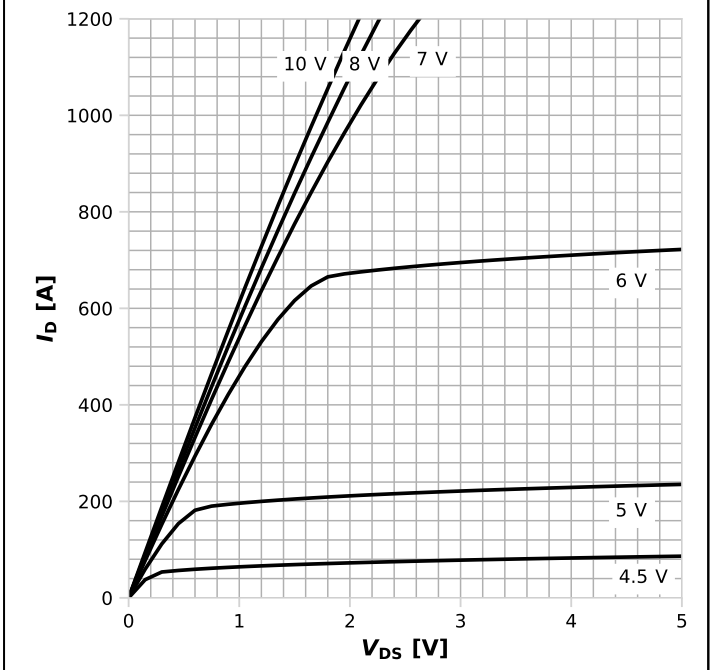
I_D=f(V_{DS}); T_C=25 °C; D=0; parameter: t_p

Diagram 4: Max. transient thermal impedance



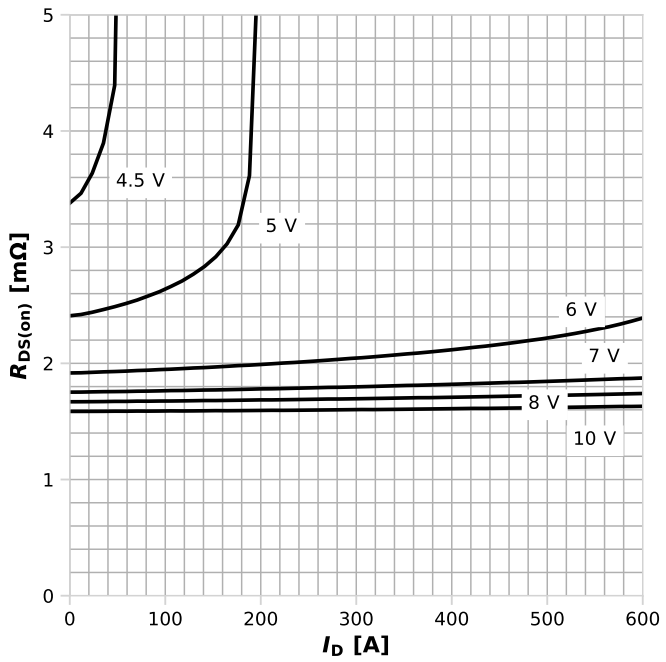
Z_{thJC}=f(t_p); parameter: D=t_p/T

Diagram 5: Typ. output characteristics



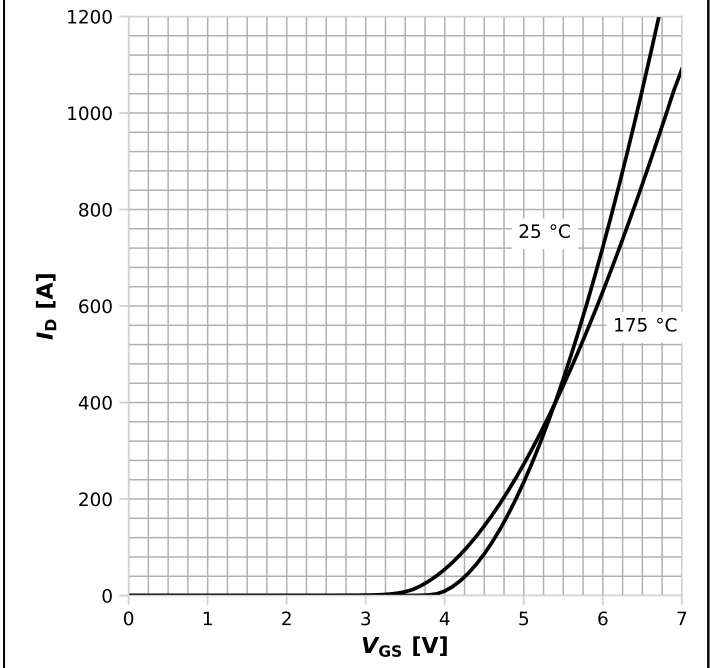
I_D=f(V_{DS}), T_j=25 °C; parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



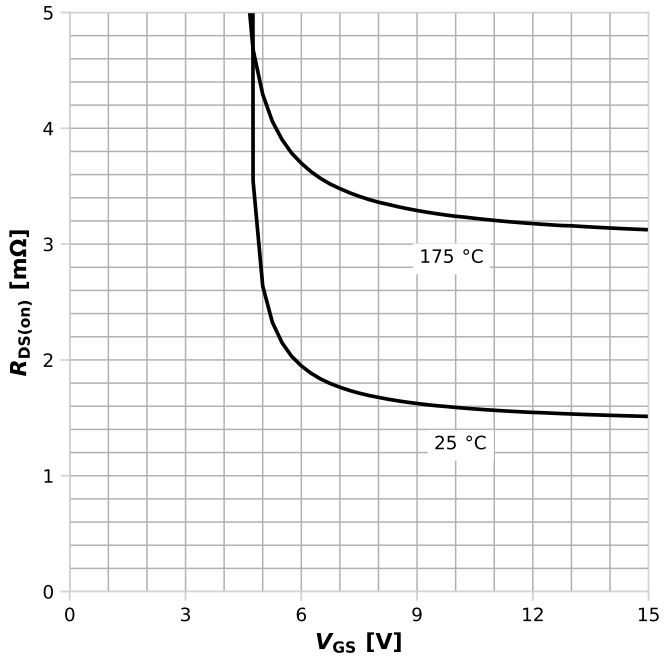
$R_{DS(on)}$=f(I_D), T_j=25 °C; parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



I_D=f(V_{GS}), $|V_{DS}|>2|I_D|R_{DS(on)max}$; parameter: T_j

Diagram 8: Typ. drain-source on resistance



$R_{DS(on)}$=f(V_{GS}), I_D=150 A; parameter: T_j

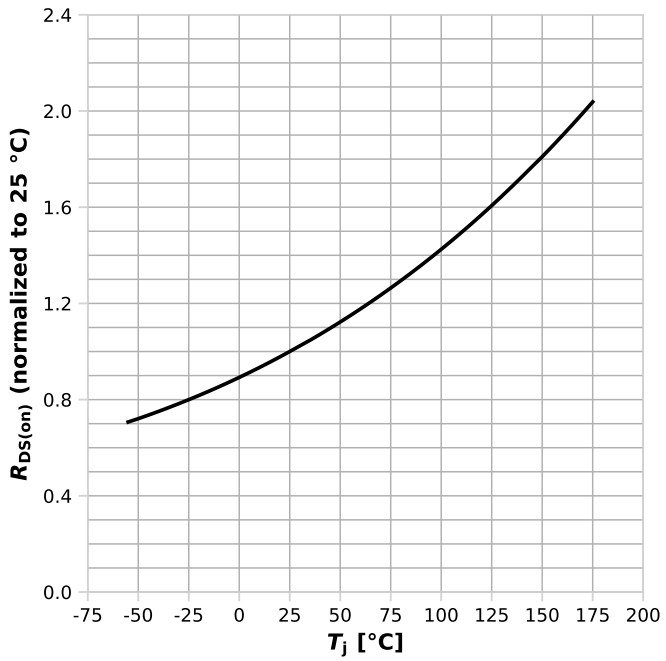
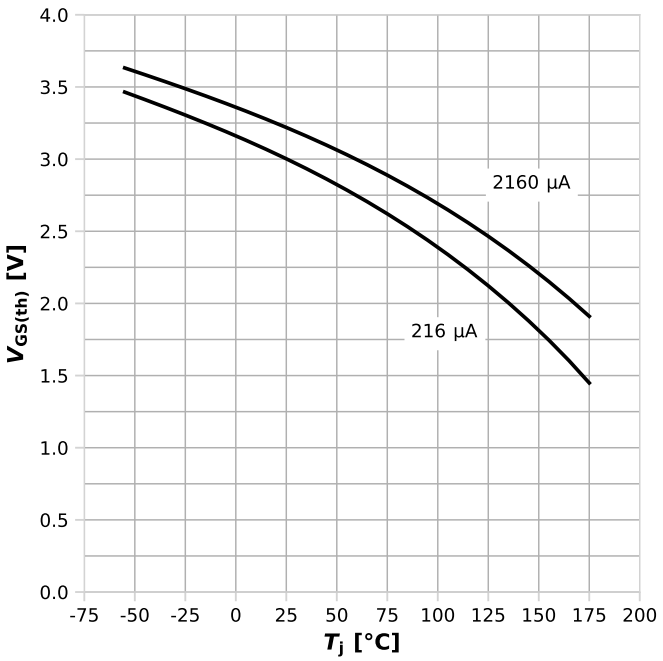
Diagram 9: Normalized drain-source on resistance	Diagram 10: Typ. gate threshold voltage
	
$R_{DS(on)}$=f(T_j), I_D=150 A, V_{GS}=10 V	$V_{GS(th)}$=f(T_j), V_{GS}=V_{DS}; parameter: I_D

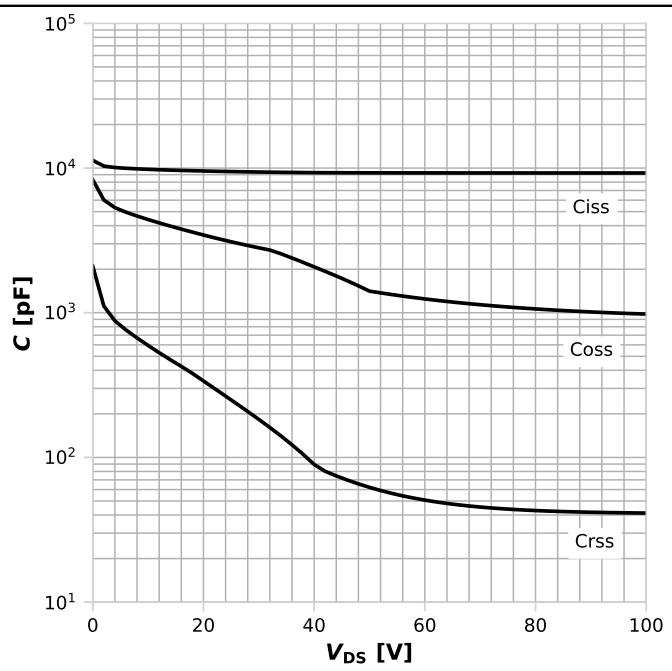
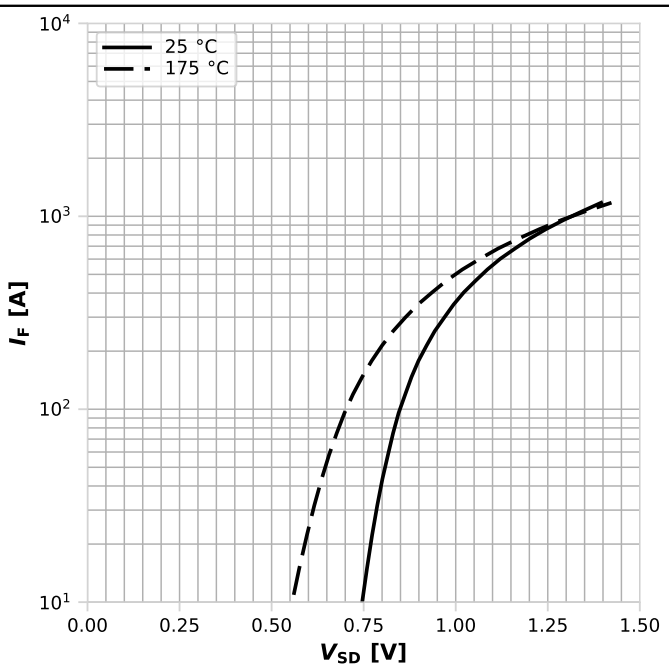
Diagram 11: Typ. capacitances	Diagram 12: Typ. forward characteristics of reverse diode
	
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz	I_F=f(V_{SD}); parameter: T_j

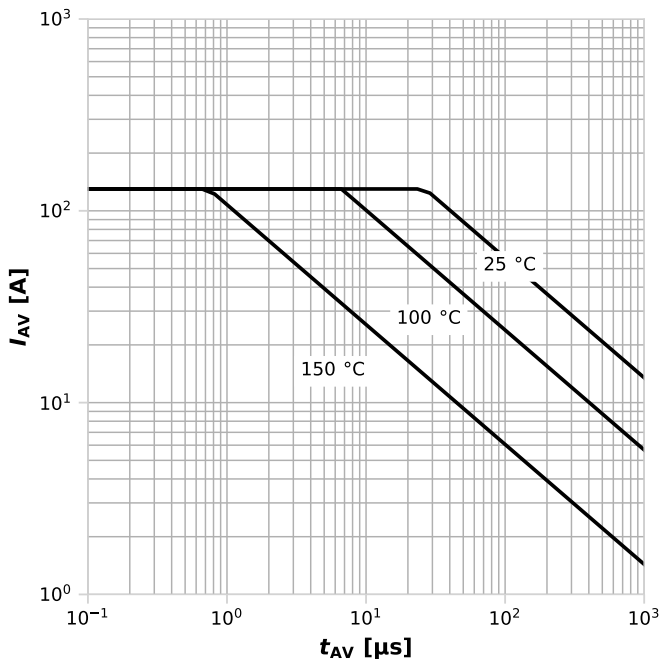
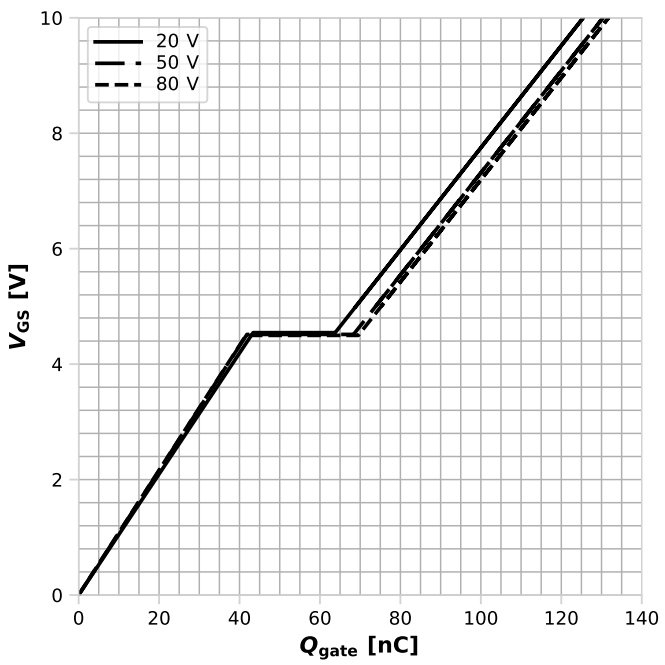
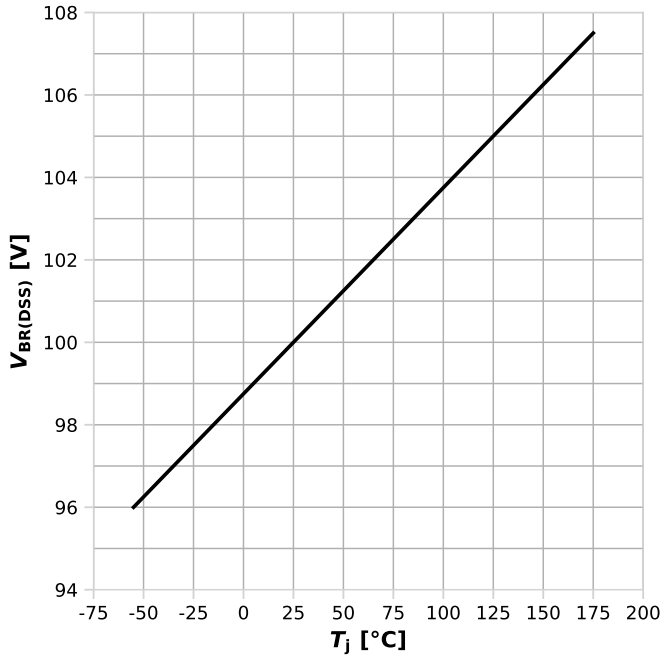
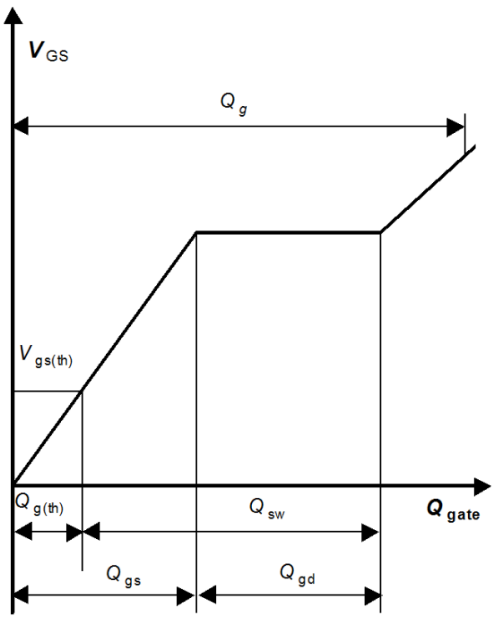
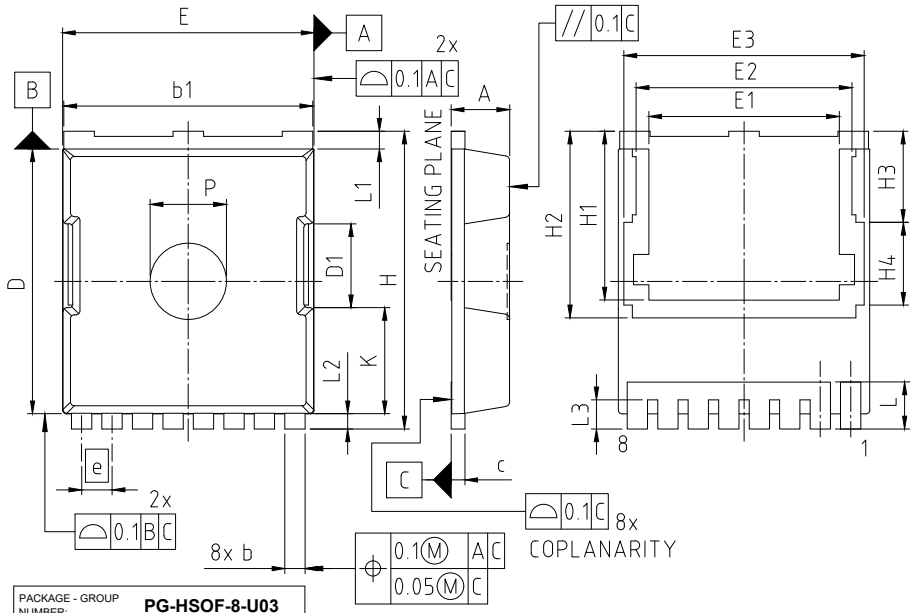
Diagram 13: Avalanche characteristics	Diagram 14: Typ. gate charge
	
I_{AS}=f(t_{AV}); R_{GS}=25 Ω; parameter: $T_{j,start}$	V_{GS}=f(Q_{gate}), I_D=100 A pulsed, T_j=25 °C; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage	Gate charge waveforms
	
$V_{BR(DSS)}$=f(T_j); I_D=1 mA	-

5 Package outlines



PACKAGE - GROUP NUMBER:	PG-HSOF-8-U03	
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	2.20	2.40
b	0.70	0.90
b1	9.70	9.90
c	0.40	0.60
D	10.28	10.58
D1	3.15	3.45
E	9.70	10.10
E1	7.35	7.65
E2	8.50	
E3	9.46	
e	1.20 (BSC)	
H	11.48	11.98
H1	6.55	6.95
H2	7.35	
H3	3.59	
H4	3.26	
N	8	
K	4.03	4.33
L	1.60	2.10
L1	0.55	0.85
L2	0.45	0.75
L3	1.00	1.30
P	2.90	3.10

Note 1: Lead length up to anti flash profile, mold flashes excluded.

Figure 1 Outline PG-HSOF-8, dimensions in mm

Revision history

IPT017N10NF2S

Revision 2025-04-29, Rev. 2.1

Previous revisions

Revision	Date	Subjects (major changes since last revision)
2.0	2022-08-04	Release of final version
2.1	2025-04-29	Update SOA diagram

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